



Lead free solder wire IF 14-16

INTERFLUX®
ELECTRONICS N.V.



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Lead free, No-clean and halide free solder wire

Description:

Interflux® **IF 14-16** Lead-Free, No-Clean solder wire contains no rosin, no halides and is recommended when soldering in **class 3** (IPC-A-610). Since the body of the IF 14 flux carrier can evaporate by heat (rather than carbonising), it is extremely suited for Lead-Free soldering.



Availability

Flux type: IF 14
Flux content: 1,6% w/w (same volume as 1,4% w/w when using Sn63Pb37)

alloy	melting point	diameters					
		0,35	0,50	0,70	1,00	1,50	2,00
Sn96,5Ag3Cu0,5	217°C—219°C	●	●	●	●	●	●
Sn96,5Ag3,5	221°C	●	●	●	●	●	●
Sn95,5Ag3,8Cu0,7	217°C-219°C	●	●	●	●	●	●
Sn99,3Cu0,7	227°C	●	●	●	●	●	●

● = available ● = upon request

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Key advantages:

- Reduced contamination of tools, equipment, due to the low flux content
- No colophony fumes
- Classification to IPC and EN: **RE LO**
- Absolutely Halogen Free
- Long tip-life
- Long product history
- Very good wetting on Cu, Ag, Sn ...



Work instructions

Manual soldering

The working temperature is between 360°C and 390°C. For more dense metals like Nickel, the temperature may be elevated to 420°C.

Choose the correct soldering tip: to reduce the thermal resistance, it is important to create a large contact surface with the component and

solder pad.

The use of a good soldering station is important in order to always have the correct temperature on the soldering joint. Use a soldering station with a response time as short as possible.

Heat up the surfaces of both component and island simultaneously. Slightly touch with the solder wire,

the point where component lead, soldering island and soldering tip meet (the small quantity of solder ensures a drastic lowering of the thermal resistance). Add subsequently without interruption, the correct amount of solder close to the soldering tip without touching the tip. It is important that no solder wire is making contact with

the soldering tip during soldering to avoid flux spitting and premature flux consumption!

Handling

Storage

Store the solder wire in a clean environment between 0°C and 40°C

Handling

To avoid spool and wire damage, handle package with care



Test results

conform EN 61190-1-3(2007) and IPC J-STD-004

Property	Result	Method
Chemical		
flux designator	RE / LO	J-STD-004
	F-SW 33	DIN 8511
	1.2.3	ISO 9454
qualitative copper mirror	pass	J-STD-004 IPC-TM-650 2.3.32
qualitative halide		
silver chromate (Cl, Br)	pass	J-STD-004 IPC-TM-650 2.3.33
spot test (F)	pass	J-STD-004 IPC-TM-650 2.3.35.1
quantitative halide	0,0%	J-STD-004 IPC-TM-650 2.3.35
Environmental		
SIR test	pass	J-STD-004 IPC-TM-650 2.6.3.3
	pass	TA-NWT-000078 13.1.4
qualitative corrosion, flux	pass	J-STD-004 IPC-TM-650 2.6.15
electro chemical migration	pass	TA-NWT-000078 13.1.5



Packaging

Spools of 100g, 450g, 500g and 1000g

D i s c l i m e r

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